

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of

Confirmation No.: **4400**

**GIJSMAN et al**

Atty. Ref.: **4662-123**

Serial No. **10/563,378**

Group: **1796**

Filed: **January 5, 2006**

Examiner: **Nguyen**

For: **HEAT STABILIZED MOULDING COMPOSITION**

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June 8, 2010

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**LETTER ACCOMPANYING PART B -- FEE(S) TRANSMITTAL**

Sir:

Applicant respectfully submits concurrently herewith the new Part B – Fee(s) Transmittal Form for the above-identified application. No fee is required to be paid at this time since the issue and publication fees were already paid on February 1, 2010, based on the Notice of Allowance mailed November 2, 2009. It is requested that the previously paid issue fee be applied to the current issue fee as required by the new Notice of Allowance mailed March 10, 2010.

Respectfully submitted,

**NIXON & VANDERHYE P.C.**

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